



WP130WDT/GYW T-1 (3mm) Single-Level Circuit Board Indicator

DESCRIPTIONS

- The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode
- The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode

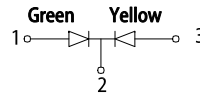
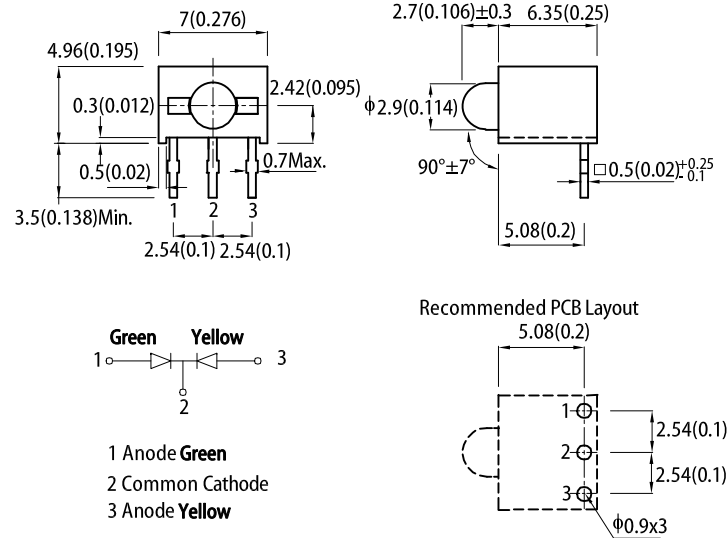
FEATURES

- Pre-trimmed leads for pc board mounting
- 3 leads with common lead
- Black case enhances contrast ratio
- Housing UL rating: 94V-0
- Housing material: Type 66 nylon
- RoHS compliant

APPLICATIONS

- Status indicator
- Illuminator
- Signage applications
- Decorative and entertainment lighting
- Commercial and residential architectural lighting

PACKAGE DIMENSIONS



1 Anode **Green**
2 Common Cathode
3 Anode **Yellow**

- Notes:
1. All dimensions are in millimeters (inches).
 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
 3. Lead spacing is measured where the leads emerge from the package.
 4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA ^[2]		Viewing Angle ^[1]
			Min.	Typ.	2θ1/2
WP130WDT/GYW	■ Green (GaP)	White Diffused	18	40	60°
	■ Yellow (GaAsP/GaP)		10	20	

Notes:
1. $\theta 1/2$ is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous flux: +/-15%.
3. Luminous intensity value is traceable to CIE127-2007 standards.

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		Unit
			Typ.	Max.	
Wavelength at Peak Emission I _F = 20mA	λ _{peak}	Green Yellow	565 590	-	nm
Dominant Wavelength I _F = 20mA	λ _{dom} [1]	Green Yellow	568 588	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	Green Yellow	30 35	-	nm
Capacitance	C	Green Yellow	15 20	-	pF
Forward Voltage I _F = 20mA	V _F [2]	Green Yellow	2.2 2.1	2.5 2.5	V
Reverse Current (V _R = 5V)	I _R	Green Yellow	-	10 10	uA
Temperature Coefficient of λ _{peak} I _F = 20mA, -10°C ≤ T ≤ 85°C	TC _{λpeak}	Green Yellow	0.1 0.12	-	nm/°C
Temperature Coefficient of λ _{dom} I _F = 20mA, -10°C ≤ T ≤ 85°C	TC _{λdom}	Green Yellow	0.06 0.07	-	nm/°C
Temperature Coefficient of V _F I _F = 20mA, -10°C ≤ T ≤ 85°C	TC _V	Green Yellow	-2 -2	-	mV/°C

Notes:

1. The dominant wavelength (λ_d) above is the setup value of the sorting machine. (Tolerance λ_d : ±1nm.)
2. Forward voltage: ±0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

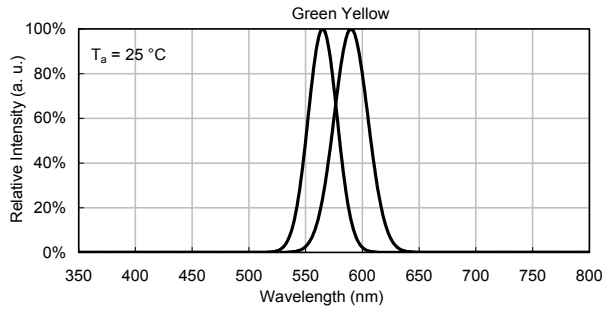
Parameter	Symbol	Value		Unit
		Green	Yellow	
Power Dissipation	P _D	62.5	75	mW
Reverse Voltage	V _R	5	5	V
Junction Temperature	T _j	110	110	°C
Operating Temperature	T _{op}	-40 to +85		°C
Storage Temperature	T _{stg}	-40 to +85		°C
DC Forward Current	I _F	25	30	mA
Peak Forward Current	I _{FM} [1]	140	140	mA
Electrostatic Discharge Threshold (HBM)	-	8000	8000	V
Thermal Resistance (Junction / Ambient)	R _{th JA} [2]	500	500	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} [2]	330	300	°C/W
Lead Solder Temperature [3]		260°C For 3 Seconds		
Lead Solder Temperature [4]		260°C For 5 Seconds		

Notes:

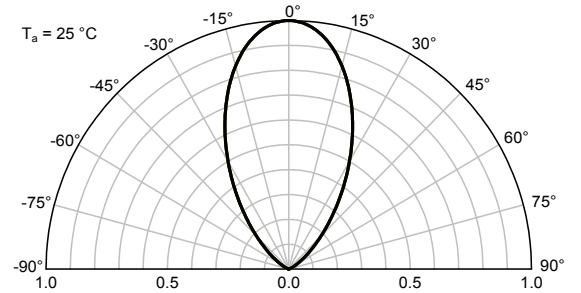
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. R_{th JA}, R_{th JS} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad).
3. 2mm below package base.
4. 5mm below package base.
5. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

TECHNICAL DATA

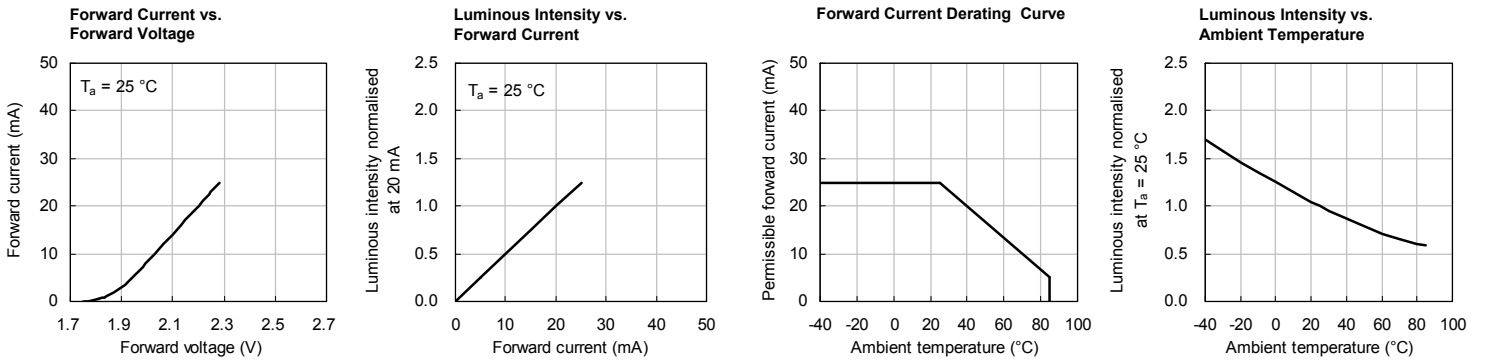
RELATIVE INTENSITY vs. WAVELENGTH



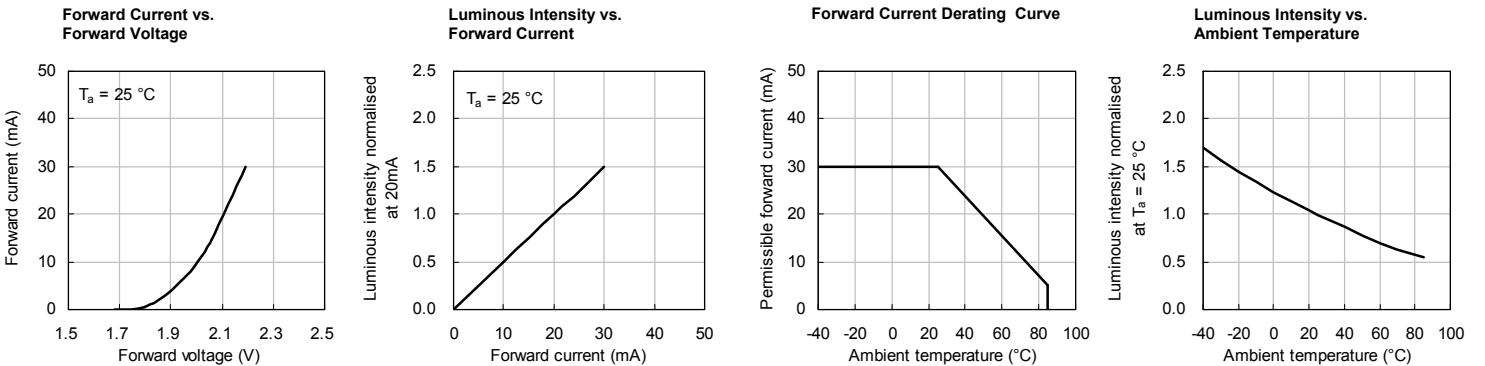
SPATIAL DISTRIBUTION



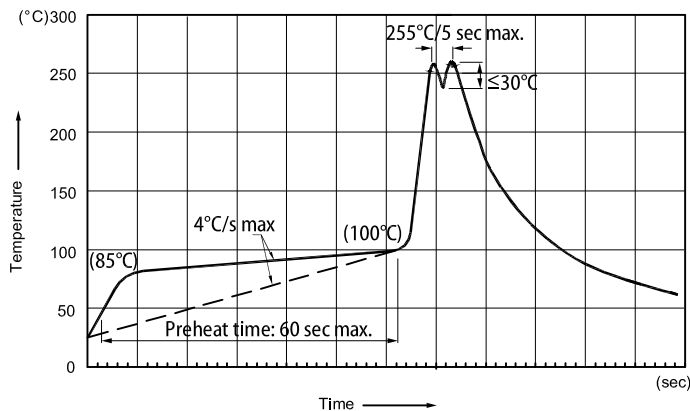
GREEN



YELLOW



RECOMMENDED WAVE SOLDERING PROFILE



Notes:

1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.

